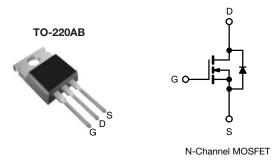
# SiHP15N60E

**Vishay Siliconix** 



# **E Series Power MOSFET**



PRODUCT SUMMARY					
V <sub>DS</sub> (V) at T <sub>J</sub> max.	650				
R <sub>DS(on)</sub> max. (Ω) at 25 °C	$V_{GS} = 10 V$	0.28			
Q <sub>g</sub> max. (nC)	78				
Q <sub>gs</sub> (nC)	9				
Q <sub>gd</sub> (nC)	17				
Configuration	Single				

### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q<sub>q</sub>)
- Avalanche energy rated (UIS)
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	SiHP15N60E-E3
Load (Ph) free and helegen free	SiHP15N60E-BE3 <sup>a</sup>
Lead (Pb)-free and halogen-free	SiHP15N60E-GE3

Note

a. "-BE3" denotes alternate manufacturing location

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub>	= 25 °C, un	less otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V <sub>DS</sub>	600	V	
Gate-source voltage			V <sub>GS</sub>	± 30	V	
Continuous drain current ( $T_J = 150 \ ^\circ C$ )	V <sub>GS</sub> at 10 V	$T_{C} = 25 \text{ °C}$ $T_{C} = 100 \text{ °C}$	1	15		
	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C	l <sub>D</sub>	9.6	А	
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	39		
Linear derating factor				1.4	W/°C	
Single pulse avalanche energy <sup>b</sup>			E <sub>AS</sub>	102	mJ	
Maximum power dissipation			P <sub>D</sub>	180	W	
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-source voltage slope	$V_{DS} = 0 V \text{ to } 80 \% V_{DS}$		d\//dt	70	1//	
Reverse diode dV/dt <sup>d</sup>		dV/dt	7.7	V/ns		
Soldering recommendations (peak temperature) <sup>c</sup>	For 10 s			300	°C	

#### Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

b.  $V_{DD} = 50$  V, starting  $T_J = 25$  °C, L = 11.6 mH,  $R_a = 25 \Omega$ ,  $I_{AS} = 4.2$  A

c. 1.6 mm from case

d.  $I_{SD} \leq I_D$ , dI/dt = 100 A/µs, starting T<sub>J</sub> = 25 °C

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PARAMETER	SYMBOL	TYP.		MAX.		UNIT		
Maximum junction-to-ambient	R <sub>thJA</sub>	-	- 62					
Maximum junction-to-case (drain)	R <sub>thJC</sub>	- 0.7			°C/W			
	1100							
<b>SPECIFICATIONS</b> ( $T_J = 25 \ ^{\circ}C$ , u	Inless otherwi	ise noted)						
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNI
Static								
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> =	= 0 V, I <sub>D</sub> = 2	50 μA	600	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I <sub>D</sub> = 1 mA		l <sub>D</sub> = 1 mA	-	0.71	-	V/°(
Gate-source threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$		2	-	4	V
		$V_{GS} = \pm 20 V$ $V_{GS} = \pm 30 V$		-	-	± 100	nA	
Gate-source leakage	I <sub>GSS</sub>			-	-	± 1	μA	
Zero gate voltage drain current		V <sub>DS</sub> =	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V		-	-	1	
	IDSS	V <sub>DS</sub> = 480 V	, V <sub>GS</sub> = 0 V	, T <sub>J</sub> = 125 °C	-	-	10	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I	<sub>D</sub> = 8 A	-	0.23	0.28	Ω
Forward transconductance	9 <sub>fs</sub>	V <sub>DS</sub>	= 30 V, I <sub>D</sub> =	= 8 A	-	4.6	-	S
Dynamic		-			•	•	•	
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$ f = 1 MHz			-	1350	-	
Output capacitance	C <sub>oss</sub>			-	70	-		
Reverse transfer capacitance	C <sub>rss</sub>			-	5	-		
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>	$V_{DS}$ = 0 V to 480 V, $V_{GS}$ = 0 V		-	53	-	pF	
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>			-	177	-		
Total gate charge	Qg		V <sub>GS</sub> = 10 V I <sub>D</sub> = 8 A, V <sub>DS</sub> = 480 V		-	39	78	nC
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V			-	11	-	
Gate-drain charge	Q <sub>gd</sub>				-	17	-	
Turn-on delay time	t <sub>d(on)</sub>				-	16	32	
Rise time	t <sub>r</sub>	- V <sub>DD</sub> =	V <sub>DD</sub> = 480 V, I <sub>D</sub> = 8 A,		-	26	52	1
Turn-off delay time	t <sub>d(off)</sub>	$V_{GS} = 10 \text{ V}, \text{ R}_{g} = 9.1 \Omega$		-	41	82	ns	
Fall time	t <sub>f</sub>			-	22	44		
Gate input resistance	R <sub>g</sub>	f = 1 MHz, open drain		0.3	0.86	1.7	Ω	
Drain-Source Body Diode Characteristic					•			
Continuous source-drain diode current	١ <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	15		
Pulsed diode forward current	I <sub>SM</sub>			-	-	60	A	
Diode forward voltage	V <sub>SD</sub>	$T_{J} = 25 \text{ °C}, I_{S} = 8 \text{ A}, V_{GS} = 0 \text{ V}$		-	1.0	1.2	V	
Reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S</sub> = 8 A, dl/dt = 100 A/ $\mu$ s, V <sub>R</sub> = 25 V		-	302	604	ns	
Reverse recovery charge	Q <sub>rr</sub>			-	4.0	8	μ	
Reverse recovery current	I <sub>RRM</sub>			-	24	-	A	

Notes

a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ 



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### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

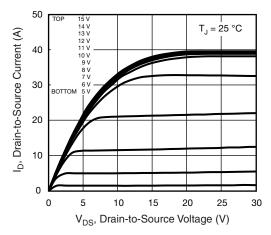


Fig. 1 - Typical Output Characteristics

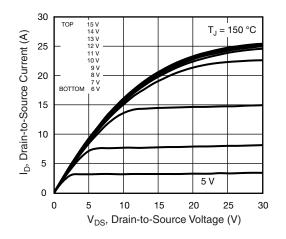


Fig. 2 - Typical Output Characteristics

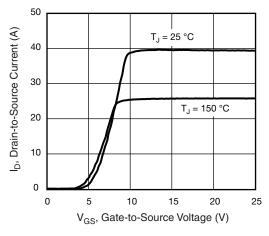


Fig. 3 - Typical Transfer Characteristics

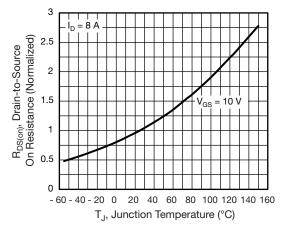


Fig. 4 - Normalized On-Resistance vs. Temperature

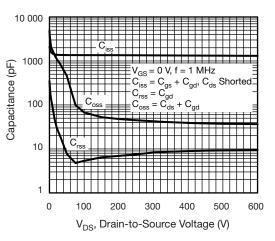


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

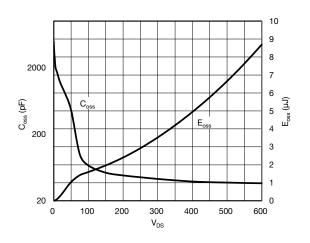


Fig. 6 -  $C_{\rm oss}$  and  $E_{\rm oss}$  vs.  $V_{\rm DS}$ 

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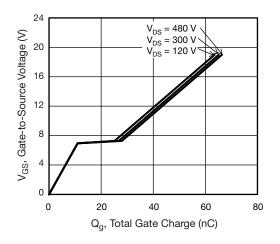


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

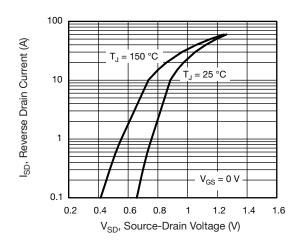


Fig. 8 - Typical Source-Drain Diode Forward Voltage

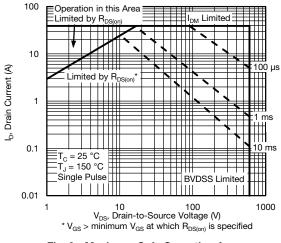


Fig. 9 - Maximum Safe Operating Area

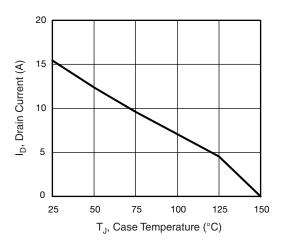


Fig. 10 - Maximum Drain Current vs. Case Temperature

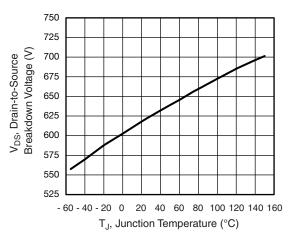


Fig. 11 - Temperature vs. Drain-to-Source Voltage

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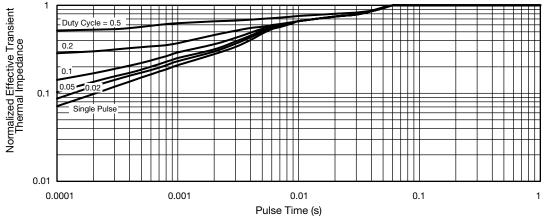


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

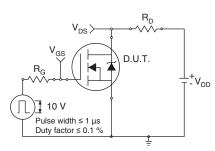


Fig. 13 - Switching Time Test Circuit

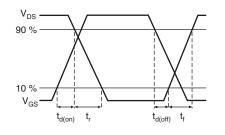


Fig. 14 - Switching Time Waveforms

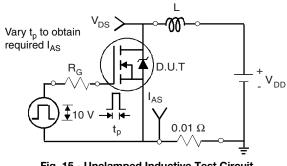


Fig. 15 - Unclamped Inductive Test Circuit

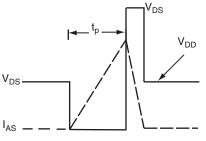


Fig. 16 - Unclamped Inductive Waveforms

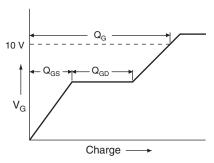
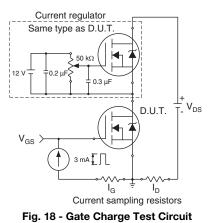


Fig. 17 - Basic Gate Charge Waveform



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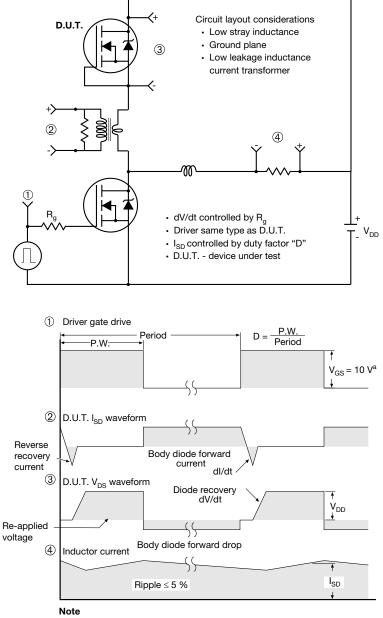
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#### Peak Diode Recovery dV/dt Test Circuit



a.  $V_{GS} = 5 V$  for logic level devices

Fig. 19 - For N-Channel

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Revision: 01-Jan-2024